BRCS2310DMF

蓝箭电子 BLUE ROCKET ELECTRONICS

DATA SHEET

/ Descriptions

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/ Features

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/ Applications

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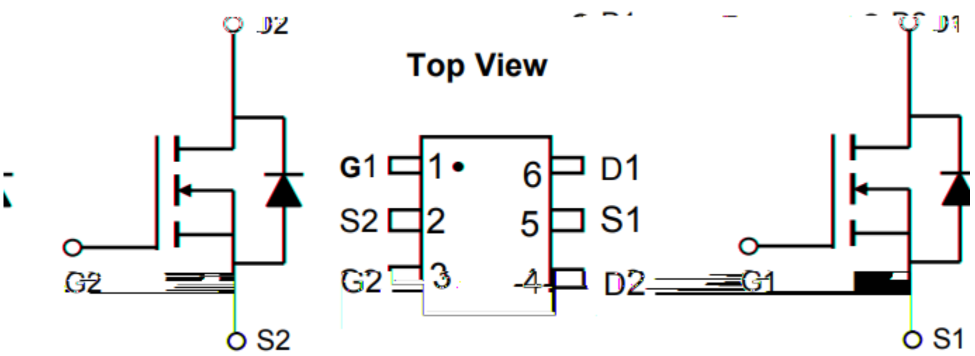
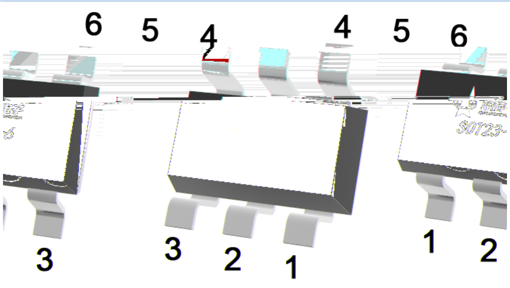
/ Equivalent Circuit



/ Pinning



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/ Marking

/ Absolute Maximum Ratings(Ta=25)

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/ Electrical Characteristics(Ta=25)

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/ Electrical Characteristic Curve

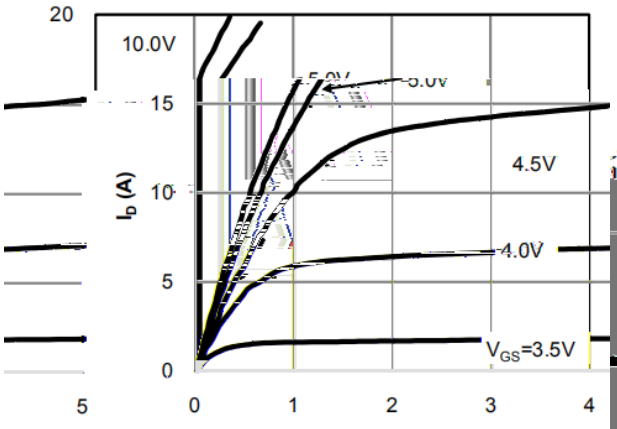
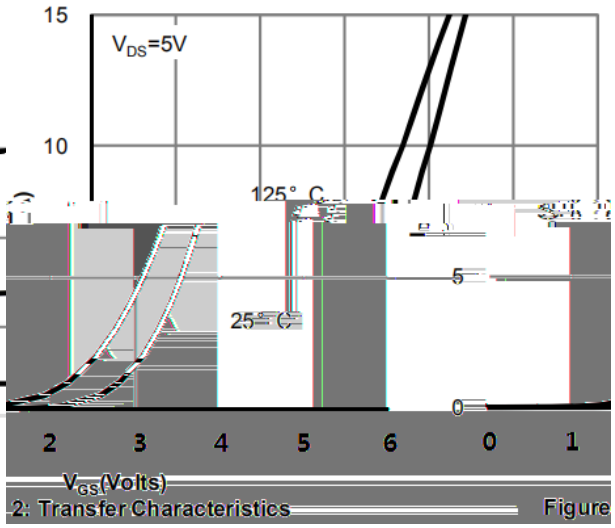
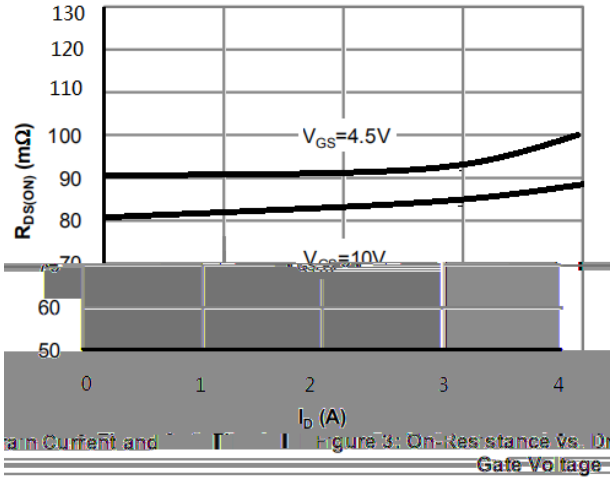


Fig 1: On-Region Characteristics



2: Transfer Characteristics Figure



Gate Voltage

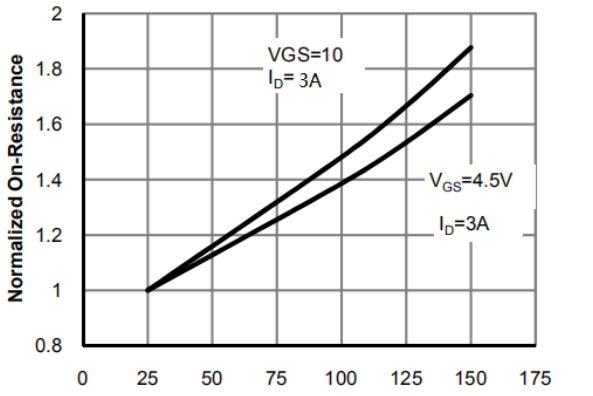


Figure 4: On-Resistance vs. Junction Temperature

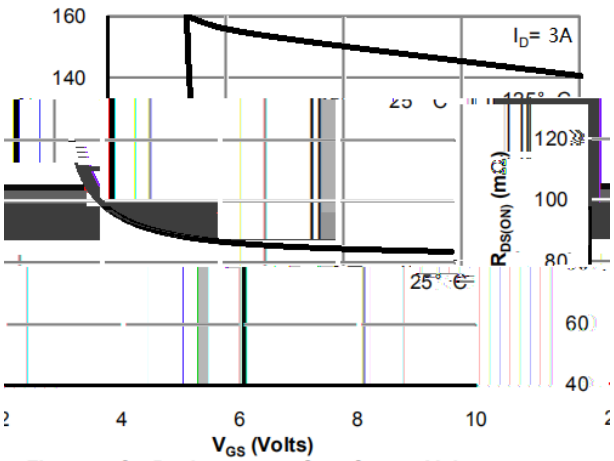


Figure 5: On-Resistance vs. Gate-Source Voltage

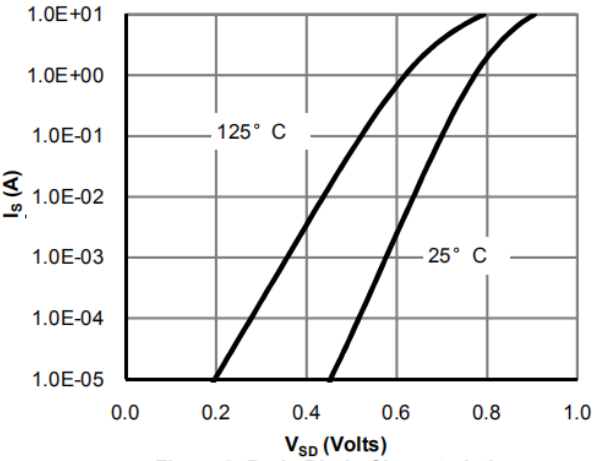
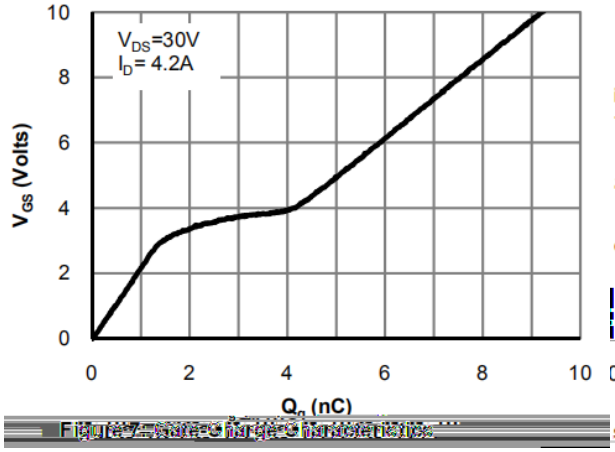
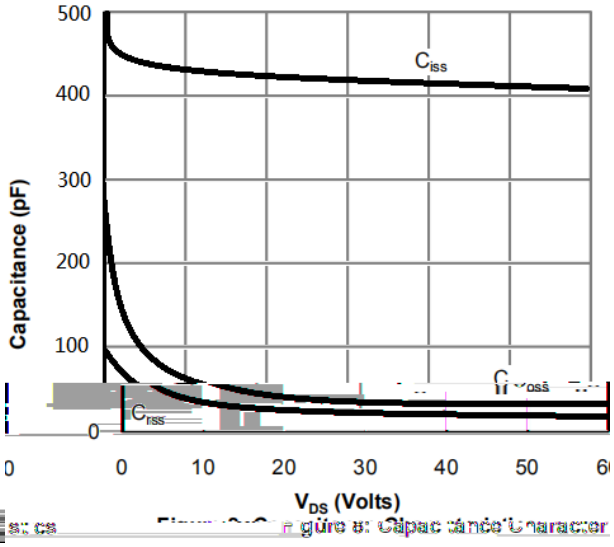
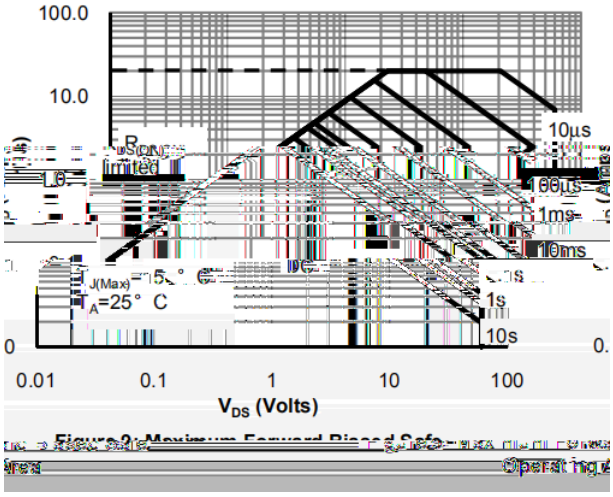


Figure 6: Body-Diode Characteristics

/ Electrical Characteristic Curve







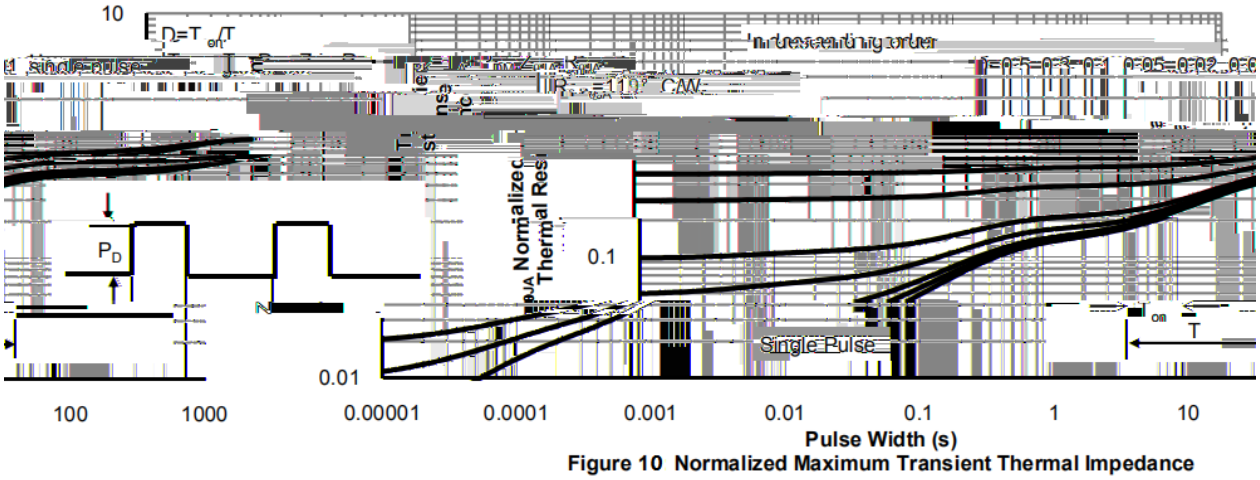


Figure 10 Normalized Maximum Transient Thermal Impedance

/ Package Dimensions

Unit: mm

rs	Symbol	Dimensions In Millimeters	
		Min	Max
	E1	0.85	1.05
	a	0.35	0.50
	c	0.10	0.20
	b	0.35	0.55
	F	0	0.15

Symbol	Dimensions In Millimete	
	Min	Max
L	2.82	3.02
B	1.50	1.70
C	0.90	1.30
L1	2.60	3.00
E	1.80	2.00

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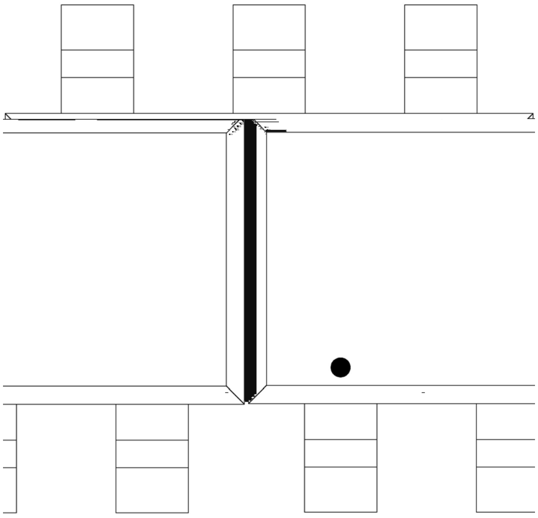
SOT

/ Marking Instructions



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( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

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/ Resistance to Soldering Heat Test Conditions

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/ Packaging SPEC.

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